TLC2272 AVAILABLE OPTIONS

T_A	V_{IO}max At 25°C	PACKAGED DEVICES					
		SMALL OUTLINE† (D)	CERAMIC LCC (FK)	CERAMIC DIP (JG)	PLASTIC DIP (P)	TSSOP‡ (PW)	CERAMIC FLAT PACK (U)
0°C to 70°C	950 μV 2.5 mV	TLC2272ACD TLC2272CD	— —	— —	TLC2272ACP TLC2272CP	TLC2272ACPW TLC2272CPW	— —
−40°C to 125°C	950 μV 2.5 mV	TLC2272AID TLC2272ID	— —	— —	TLC2272AIP TLC2272IP	— TLC2272IPW	— —
	950 μV 2.5 mV	TLC2272AQD TLC2272QD	— —	— —	—	TLC2272AQPW TLC2272QPW	— —
−55°C to 125°C	950 μV 2.5 mV	TLC2272AMD TLC2272MD	TLC2272AMFK TLC2272MFK	TLC2272AMJG TLC2272MJG	TLC2272AMP TLC2272MP	—	TLC2272AMU TLC2272MU

† The D packages are available taped and reeled. Add R suffix to the device type (e.g., TLC2272CDR).
‡ The PW package is available taped and reeled. Add R suffix to the device type (e.g., TLC2272PWR).
§ Chips are tested at 25°C.

TLC2274 AVAILABLE OPTIONS

T_A	V_{IO}max AT 25°C	PACKAGED DEVICES					
		SMALL OUTLINE† (D)	CERAMIC LCC (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)	TSSOP‡ (PW)	CERAMIC FLAT PACK (W)
0°C to 70°C	950 μV 2.5 mV	TLC2274ACD TLC2274CD	—	—	TLC2274ACN TLC2274CN	TLC2274ACPW TLC2274CPW	—
−40°C to 125°C	950 μV 2.5 mV	TLC2274AID TLC2274ID	—	—	TLC2274AIN TLC2274IN	TLC2274AIPW TLC2274IPW	—
	950 μV 2.5 mV	TLC2274AQD TLC2274QD	—	—	—	—	—
−55°C to 125°C	950 μV 2.5 mV	TLC2274AMD TLC2274MD	TLC2274AMFK TLC2274MFK	TLC2274AMJ TLC2274MJ	TLC2274AMN TLC2274MN	—	TLC2274AMW TLC2274MW

† The D packages are available taped and reeled. Add R suffix to device type (e.g., TLC2274CDR).
‡ The PW package is available taped and reeled.
§ Chips are tested at 25°C.

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